

L Number	Hits	Search Text	DB	Time stamp
1	1	("6362035").PN.	USPAT; US-PGPUB; IBM_TDB	2004/09/13 13:26
2	0	("200400132263").PN.	USPAT; US-PGPUB;	2004/09/13 13:27
3	1	("20040132263").PN.	IBM_TDB USPAT; US-PGPUB;	2004/09/13 13:27
-	14	lee-jae-kyu.in.	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:53
-	1703	(438/424,433,435,437).CCLS.	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:53
-	1414	((438/424,433,435,437).CCLS.) and @ad<20020724 not samsung.as.	IBM_TDB USPAT; US-PGPUB;	2004/09/13 10:34
-	11692	sti "shallow trench isolation"	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:53
-	14962	"trench isolation" (sti "shallow trench isolation")	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:54
-	76730	well with (resistance shallow)	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:54
-	13658	well near low	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:54
-	2096	(well with (resistance shallow)) and (well near low)	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:54
-	41	((well with (resistance shallow)) and (well near low)) and ("trench isolation" (sti "shallow trench isolation"))	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:54
-	34	((well with (resistance shallow)) and (well near low)) and ("trench isolation" (sti "shallow trench isolation")))) and @ad<20020724 not samsung.as.	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:56
-	44963	ion with implantation	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:57
-	400	(ion with implantation) and (((438/424,433,435,437).CCLS.) and @ad<20020724 not samsung.as.)	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:57
-	5449	(ion with implantation) and ("trench isolation" (sti "shallow trench isolation"))	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:57
-	45909	low near (energy dose)	IBM_TDB USPAT; US-PGPUB;	2004/09/10 13:57

-	3771	(low near (energy dose)) and (ion with implantation)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 13:57
-	548	((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))	USPAT; US-PGPUB; IBM_TDB	2004/09/10 13:57
-	496	((((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 13:58
-	356	(((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well) and @ad<20020724 not samsung.as.)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:31
-	351	((((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well) and @ad<20020724 not samsung.as.) and (438/\$3 257/\$3).ccls.)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 13:58
-	5449	((ion with implantation) and ("trench isolation" (sti "shallow trench isolation")))) (((((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well) and @ad<20020724 not samsung.as.) and (438/\$3 257/\$3).ccls.)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 13:58
-	731	((ion with implantation) and (((438/424,433,435,437).CCLS.) and @ad<20020724 not samsung.as.)) (((((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well) and @ad<20020724 not samsung.as.) and (438/\$3 257/\$3).ccls.)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 13:58
-	4557	nitride and (((ion with implantation) and ("trench isolation" (sti "shallow trench isolation")))) (((((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well) and @ad<20020724 not samsung.as.) and (438/\$3 257/\$3).ccls.)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:31
-	614	nitride and (((ion with implantation) and (((438/424,433,435,437).CCLS.) and @ad<20020724 not samsung.as.)) (((((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well) and @ad<20020724 not samsung.as.) and (438/\$3 257/\$3).ccls.))	USPAT; US-PGPUB; IBM_TDB	2004/09/10 13:59
-	116	(nitride and (((ion with implantation) and (((438/424,433,435,437).CCLS.) and @ad<20020724 not samsung.as.)) (((((low near (energy dose)) and (ion with implantation)) and ("trench isolation" (sti "shallow trench isolation")))) and well) and @ad<20020724 not samsung.as.) and (438/\$3 257/\$3).ccls.)) and liner	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:30
-	7406	(dual two multipled) with implantation	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:31

-	613	((dual two multipled) with implantation) and ("trench isolation" (sti "shallow trench isolation"))	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:31
-	95472	CMOS PMOS NMOS	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:31
-	387	(CMOS PMOS NMOS) and (((dual two multipled) with implantation) and ("trench isolation" (sti "shallow trench isolation"))))	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:31
-	296	((CMOS PMOS NMOS) and (((dual two multipled) with implantation) and ("trench isolation" (sti "shallow trench isolation"))))) and @ad<20020724 not samsung.as.	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:31
-	227	nitride and (((CMOS PMOS NMOS) and (((dual two multipled) with implantation) and ("trench isolation" (sti "shallow trench isolation"))))) and @ad<20020724 not samsung.as.)	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:54
-	217	(438/433).CCLS.	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:54
-	198	((438/433).CCLS.) and @ad<20020724 not samsung.as.	USPAT; US-PGPUB; IBM_TDB	2004/09/10 14:55
-	54	((("3617827") or ("3730786") or ("3885999") or ("3930909") or ("4339767") or ("4381953") or ("4412376") or ("4485552") or ("4553318") or ("4577397") or ("4641419") or ("4466178") or ("4653177") or ("4808543") or ("5015594") or ("5137837") or ("5260226") or ("5436174") or ("5627097") or ("5643822") or ("5759881") or ("5759885") or ("5780353") or ("5789288") or ("5795801") or ("5827763") or ("5874346") or ("5937287") or ("5963801") or ("5770504") or ("5861330") or ("6033949") or ("6054344") or ("6069057") or ("6177333") or ("6228726") or ("6248645") or ("6313011") or ("6342429") or ("6472301") or ("4900689") or ("4910160") or ("4997775") or ("5051805") or ("5055418") or ("5151378") or ("5206182") or ("5270224") or ("5409845") or ("5444285") or ("5447884") or ("5518937") or ("6649477") or ("6521493")).PN.	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:32
-	93	channeling with tail	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:33
-	16689	channel with stop	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:33
-	16778	channeling with tail) (channel with stop	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:33
-	71	(channeling with tail) and (438/\$3 257/\$3).ccls.	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:39

-	66	((channeling with tail) and (438/\$3 257/\$3).ccls.) and @ad<20020724 not samsung.as.	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:40
-	3350	(channel with stop) and (438/\$3 257/\$3).ccls.	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:39
-	3007	((channel with stop) and (438/\$3 257/\$3).ccls.) and @ad<20020724 not samsung.as.	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:40
-	275	((channel with stop) and (438/\$3 257/\$3).ccls.) and @ad<20020724 not samsung.as.) and (STI "shallow trench isolation")	USPAT; US-PGPUB; IBM_TDB	2004/09/13 10:40

(FILE 'HOME' ENTERED AT 13:22:31 ON 13 SEP 2004)

FILE 'INSPEC, CAPLUS' ENTERED AT 13:22:38 ON 13 SEP 2004

L1           464 S CHANNEL STOP  
L2           4114 S STI  
L3           2607 S SHALLOW TRENCH ISOLATION  
L4           16 S (L2 OR L3) AND L1  
L5           49 S WELL RESISTANCE  
L6            4 S L5 AND (L2 OR L3)